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(12) United States Design Patent
Osato

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(54) **ELECTRIC CONTACT**

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(72) Inventor: **Eichi Osato**, Musashino (JP)

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(**) Term: **15 Years**

(21) Appl. No.: **29/699,208**

(22) Filed: **Jul. 23, 2019**

(30) **Foreign Application Priority Data**

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Jan. 23, 2019	(JP)	2019-001192

(51) **LOC (13) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/154**

(58) **Field of Classification Search**
USPC D13/103, 107, 108, 110, 112, 118, 120, D13/123, 133, 137.1, 145–147, 149–156, D13/173, 177, 184, 199; D14/240, 242, D14/432–438, 435.1; D9/434; D8/323, D8/325, 326, 329, 349, 354, 389
CPC ... H01R 4/16; H01R 4/18; H01R 4/20; H01R 43/02; H01R 43/048; H01R 9/24; H01R 9/048; H01R 13/11; H01R 13/245; H01R
(Continued)

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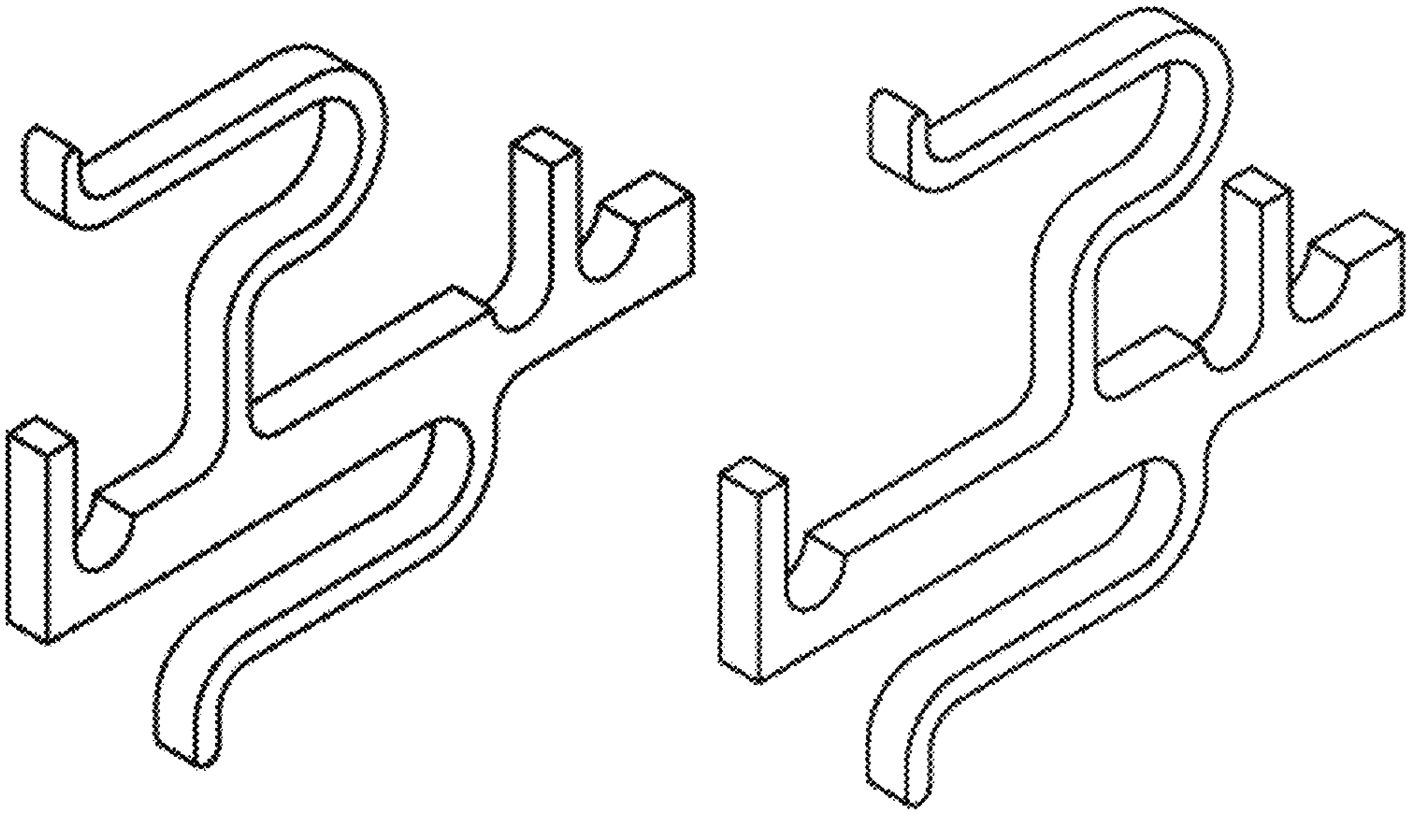
(57) **CLAIM**

The ornamental design for an electric contact, as shown and described.

DESCRIPTION

FIG. **1** is a front view of a first embodiment of an electric contact according to the present disclosure.
FIG. **2** is a rear view of the electric contact of FIG. **1**.
FIG. **3** is a right side view of the electric contact of FIG. **1**.
FIG. **4** is a left side view of the electric contact of FIG. **1**.
FIG. **5** is a top view of the electric contact of FIG. **1**.
FIG. **6** is a bottom view of the electric contact of FIG. **1**.
FIG. **7** is a top front-left perspective view of the electric contact of FIG. **1**.
FIG. **8** is a front view of a second embodiment of an electric contact according to the present disclosure.
FIG. **9** is a rear view of the electric contact of FIG. **8**.
FIG. **10** is a right side view of the electric contact of FIG. **8**.
FIG. **11** is a left side view of the electric contact of FIG. **8**.
FIG. **12** is a top view of the electric contact of FIG. **8**.
FIG. **13** is a bottom view of the electric contact of FIG. **8**; and,
FIG. **14** is a top front-left perspective view of the electric contact of FIG. **8**.
This article is an electric contact for testing and inspecting the electric characteristics of semiconductor devices such as semiconductor chips, etc.

1 Claim, 8 Drawing Sheets



(58) **Field of Classification Search**
CPC .. 13/2464; H01R 13/26; H01R 13/432; H01R 13/506; H01R 13/52; H01R 13/533; H01R 13/627; H01R 13/629
See application file for complete search history.

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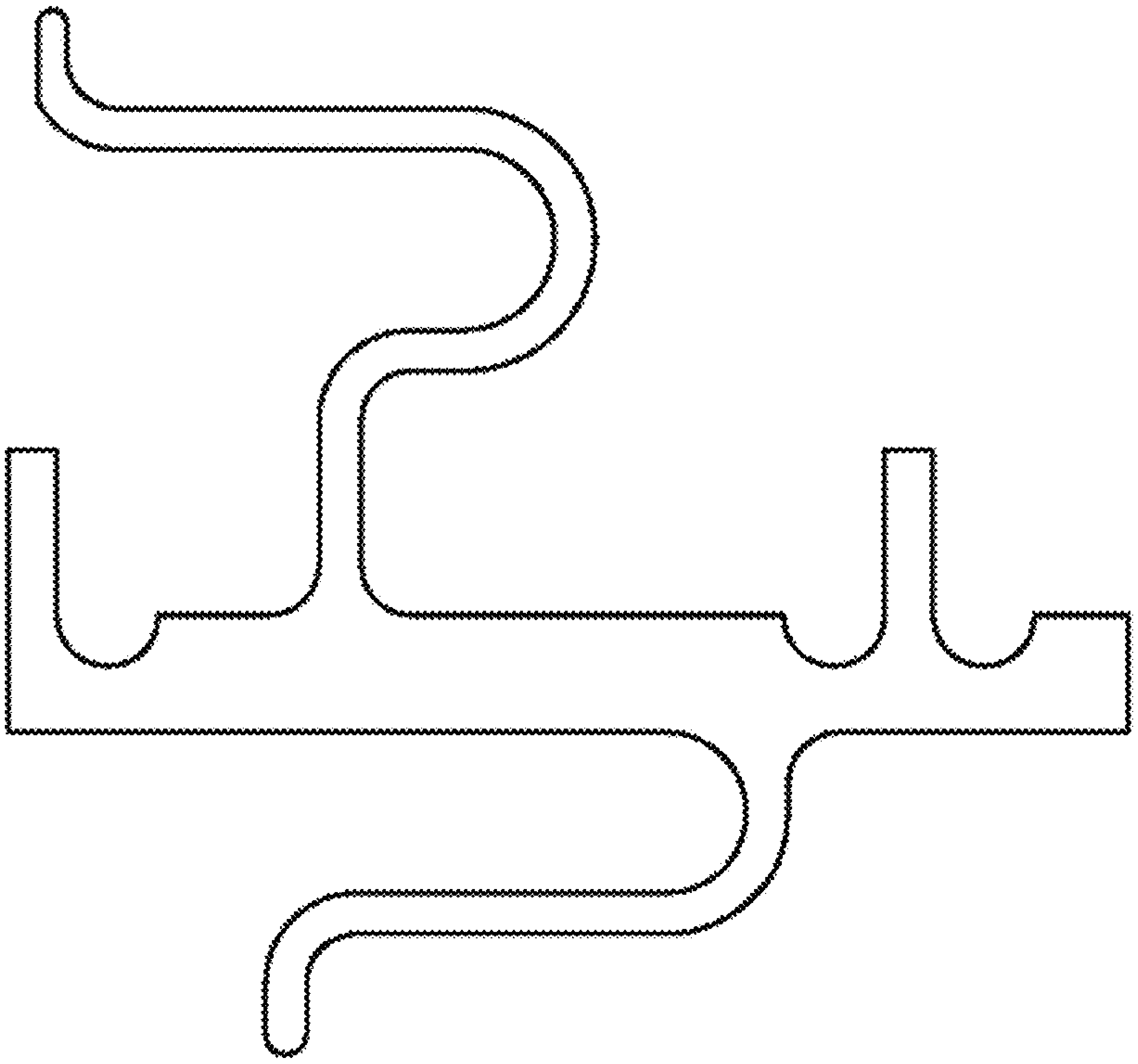


FIG. 1

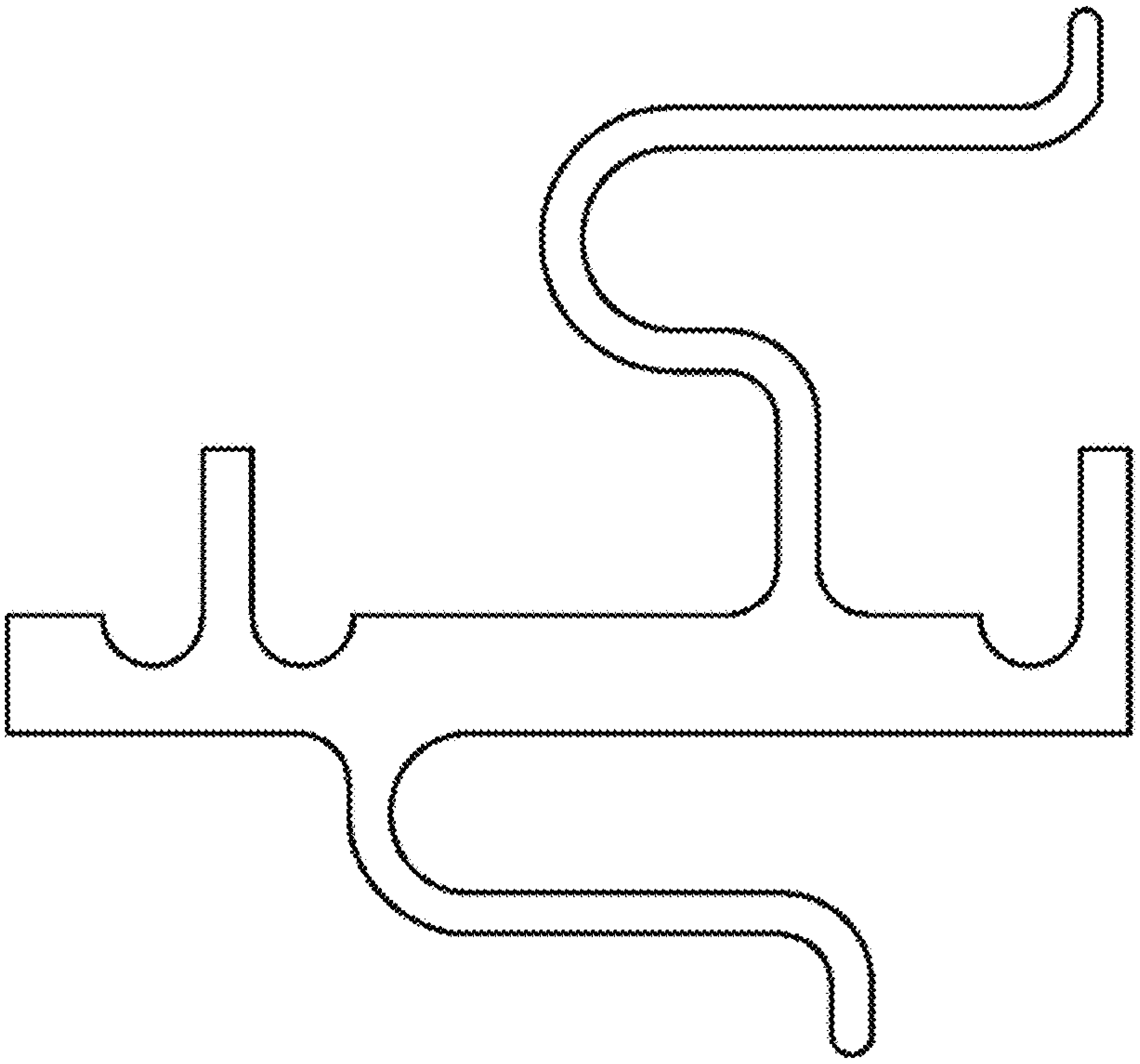


FIG. 2

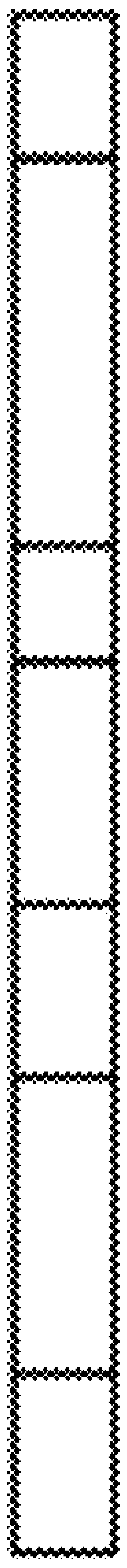
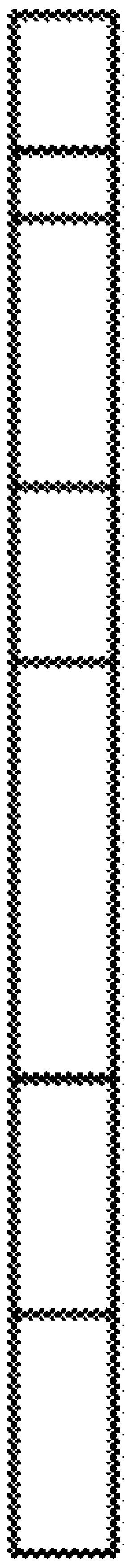


FIG. 3



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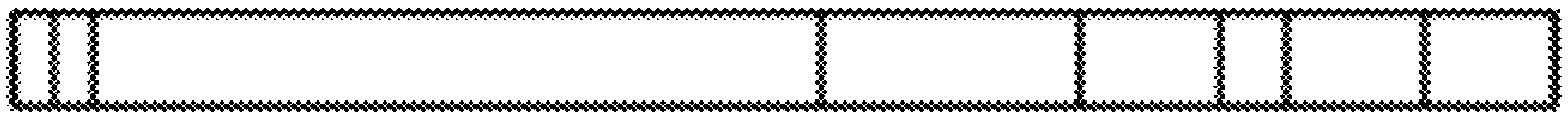

FIG. 5

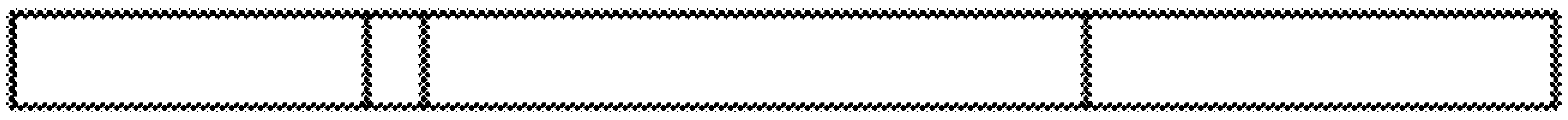

FIG. 6

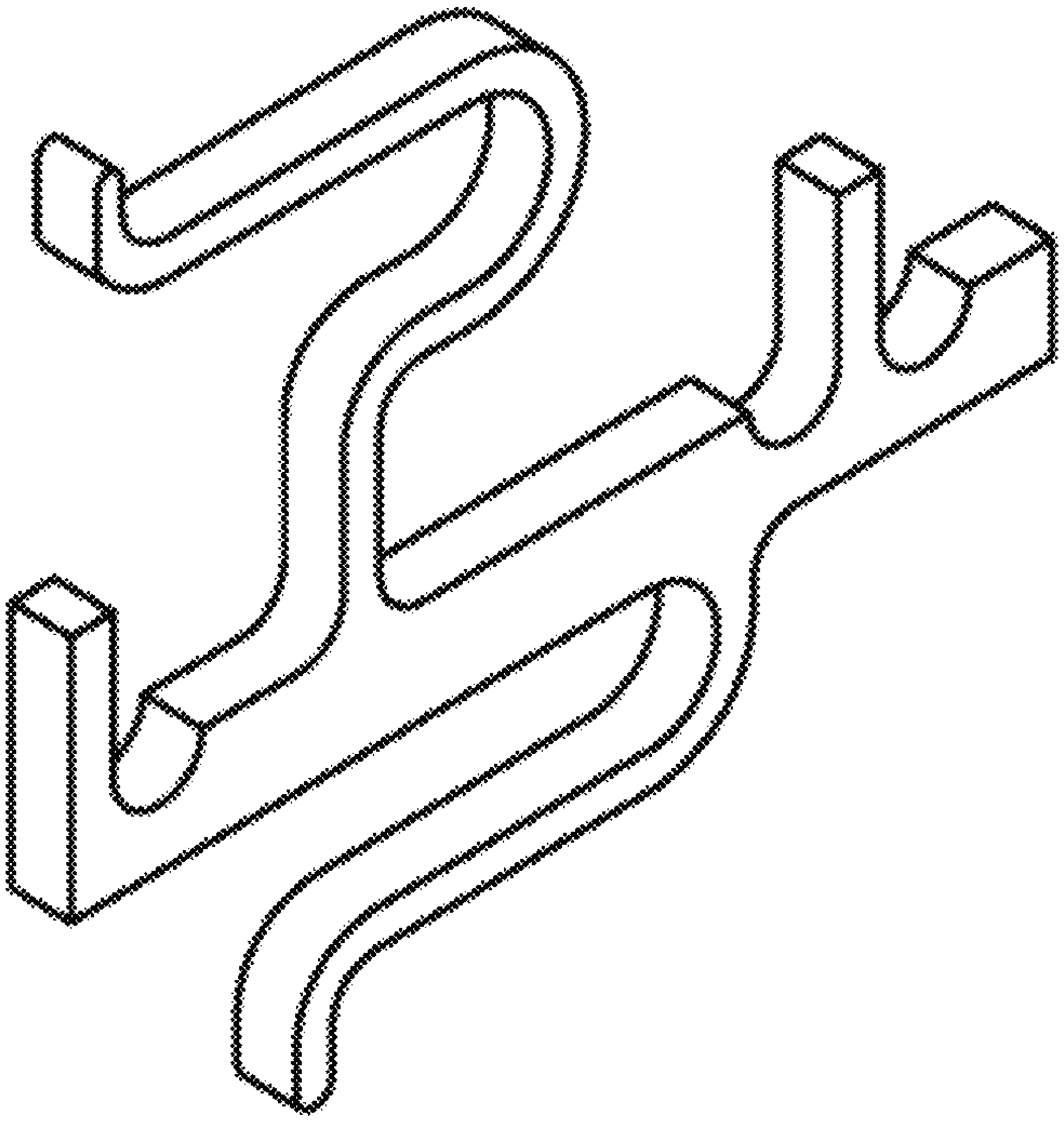

FIG. 7

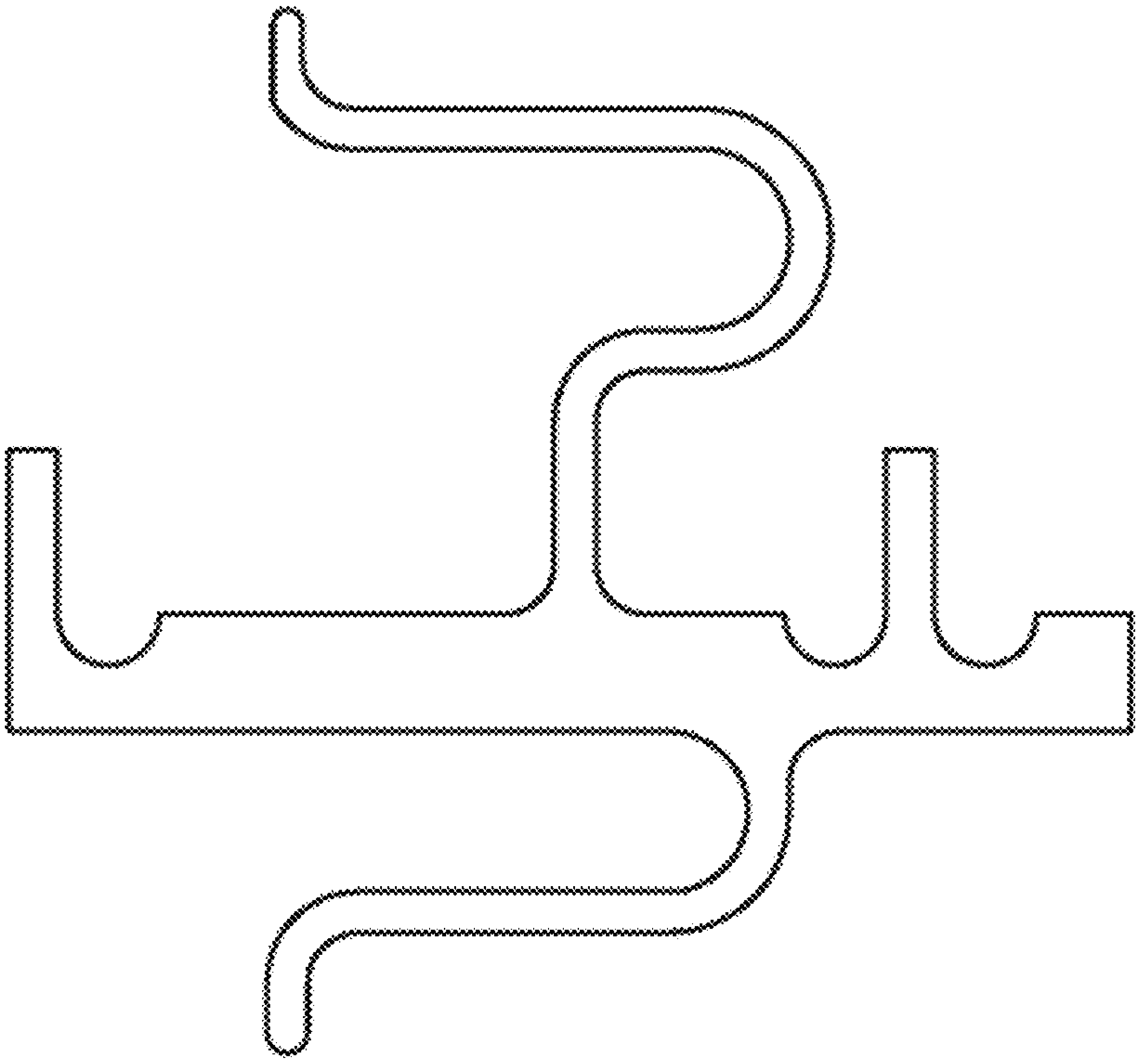

FIG. 8

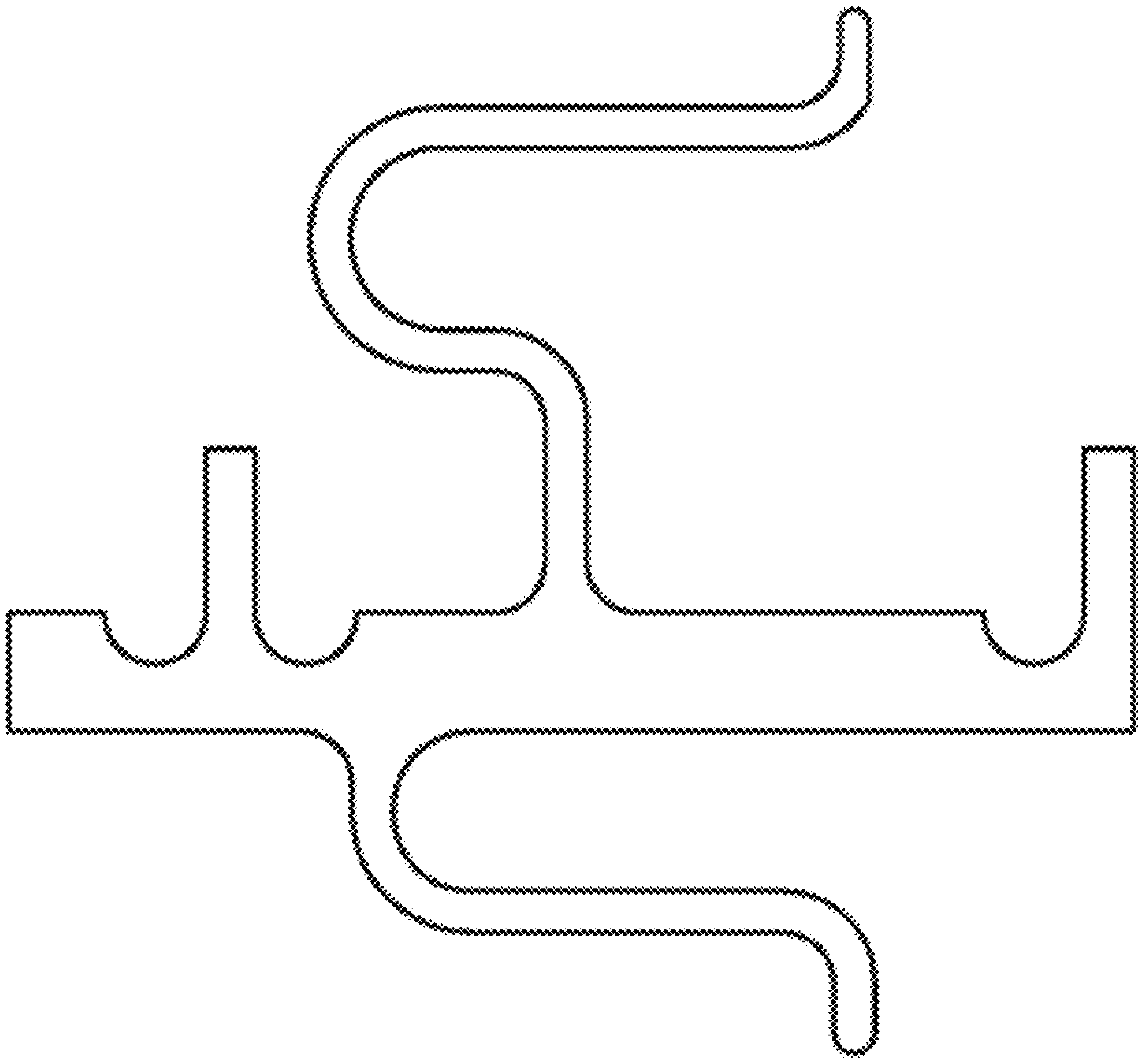

FIG. 9

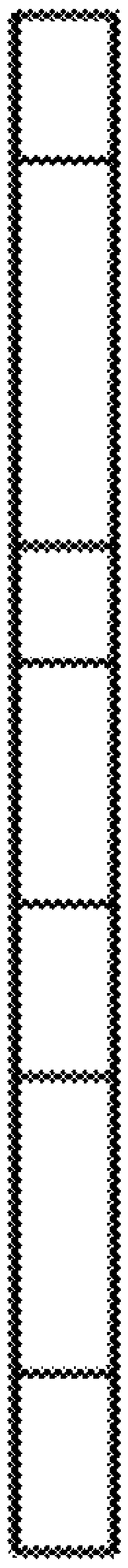

FIG. 10

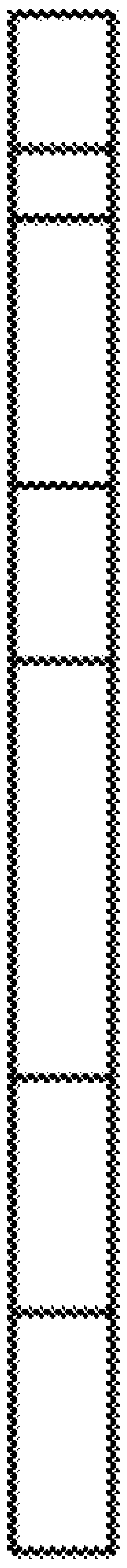

FIG. 11

FIG. 12

FIG. 13

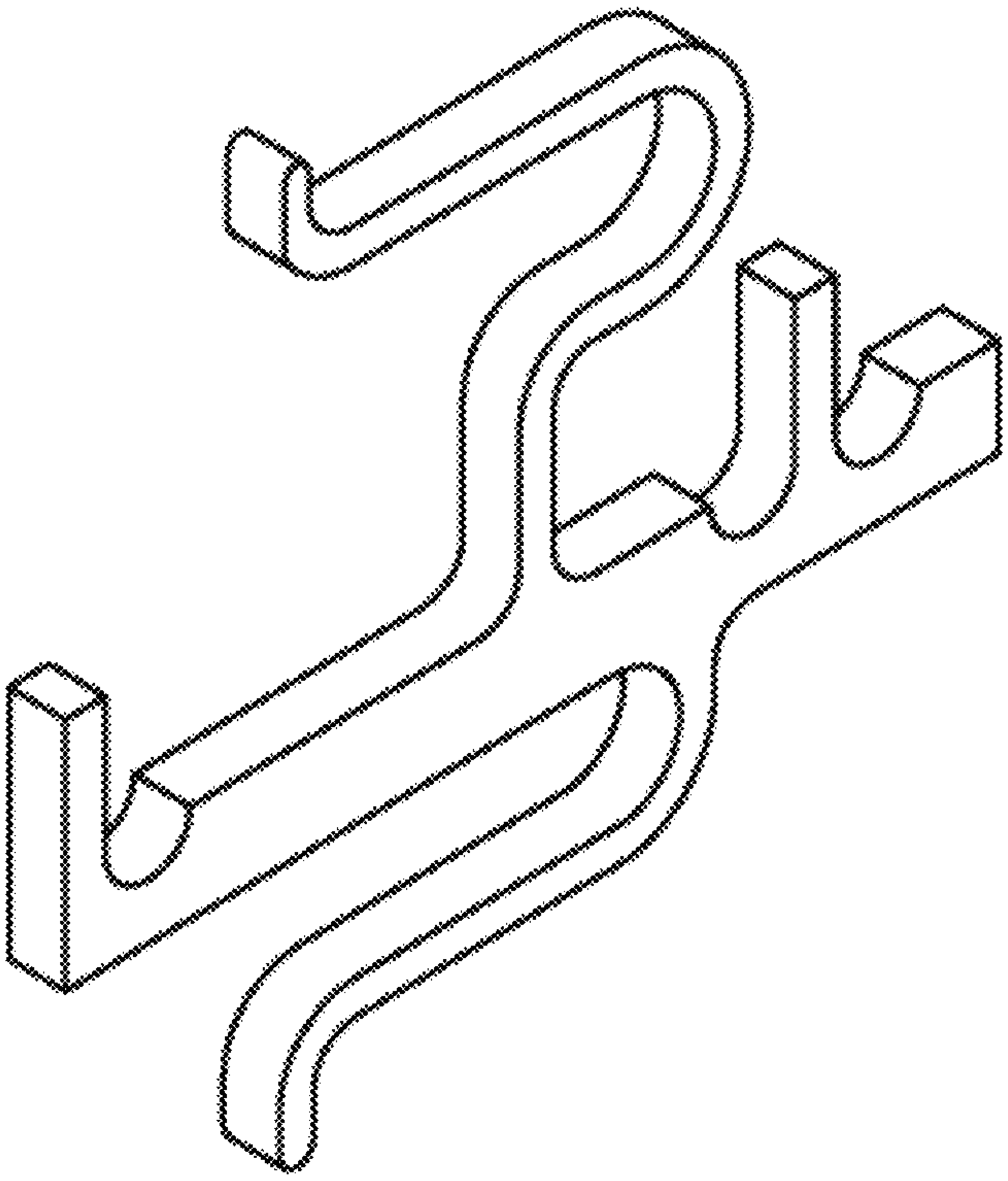

FIG. 14